


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2014 [Approved: 11 February 2025 13:25 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	4.13%	Silicon	7440-21-3	100%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	8.5%
Die attach	Other nonferrous metals	3.59%	Oxirane, [[4-(1,1-dimethylethyl)phenoxy]methyl]-	3101-60-8	10.2%
			Silver	7440-22-4	81.3%
			Carbon black	1333-86-4	0.9%
			phenolic epoxy resin	61788-97-4	7%
Encapsulation	EP (Epoxy resin)	45.16%	Epoxy resin 89	26335-32-0	8%
			Quartz sand	60676-86-0	84.1%
			COPPER, ELEMENTAL	7440-50-8	100%
Inner preparation	Copper alloys	2.29%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.87%	Tin elemental	7440-31-5	100%
Leadframe	Nickel and Nickel alloys	43.96%	Elemental iron	7439-89-6	2.6%
			COPPER, ELEMENTAL	7440-50-8	97.4%

Attached parts list

Part number	Part name
SOT-23/TO-236_PB&H-free_(JA)	Diode / Transistor SMD